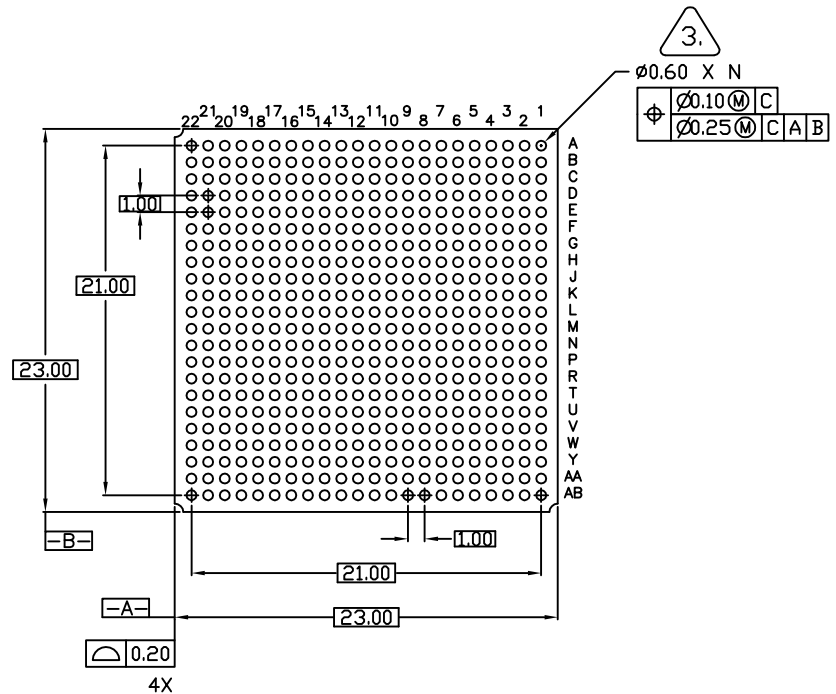
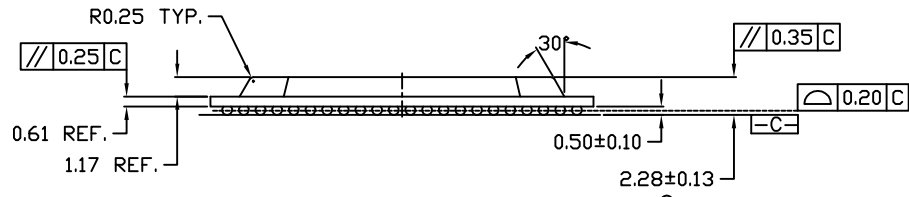


TOP VIEW



BOTTOM VIEW  
(BALL SIDE)



SIDE VIEW

- NOTES:
1. DIMENSION IS MM.
  2. THE BASIC SOLDER BALL GRID PITCH IS 1.00 MM.
  3. DIMENSION IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM  $\square$
  4. PRIMARY DATUM  $\square$  AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
  5. A1 BALL PAD CORNER I.D.
  6. MATERIAL MUST COMPLY WITH BANNED AND RESTRICTED SUBSTANCES SPEC # 10-0131.
  7. ALL DIMENSIONS APPLY TO BOTH LEADED (-) AND PbfREE (+) PKG. CODES.
  8. PACKAGE CODE: V484T-1

-DRAWING NOT TO SCALE-

<b>MAXIM</b>			
TITLE: PACKAGE OUTLINE, 484 BALLS BGA, 23MM X 23MM, 4 LAYER, 1.00MM PITCH			
APPROVAL RAMON DE LEON 02/08/10	DOCUMENT CONTROL NO. 21-0365	REV. B	1/1